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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Srinivasan Chakravarthi, et al. Docket Number: TI-33161.1

Serial No.: 10/677,610 Art Unit: 2818

Filed: 10/02/03 Examiner: Phuc T. Dang

For: Fabrication of Abrupt Ultra-Shallow Junctions

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NAME OF INVENTOR(S): Srinivasan Chakravarthi, et al.	
TITLE OF INVENTION: Fabrication of Abrupt Ultra-Shallow Junctions	
TI FILE NO.: TI-33161.1	DEPOSIT ACCT. NO.: 20-0668
FAXED: 9-9-04 DUE: 12-1-04 ATTY/SECY: RAK/tjv	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/677,610 Filing Date: 10/02/03	

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